## **OPTICAL SEMICONDUCTOR DEVICE**

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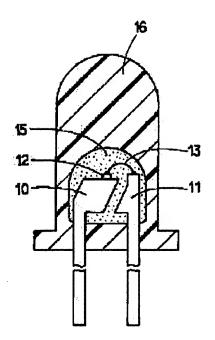
## Abstract of JP6053554

with thermoplastic resin 16.

time of resin, diversification of device profile, and reduction of resin loss.

CONSTITUTION:The optical semiconductor device comprises a pair of lead frames 10, 11, and a LED element 12 soldered to the end of one frame 10 and bonded through a gold wire 13 to the end of the other frame 11 wherein end parts of the frames 10, 11, the LED element 12, and the gold wire 13 are sealed with silicon resin 15 which is further molded

PURPOSE:To realize shortening of the setting



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